

MCT0144C6W128128PML 128 x 128		MULT	I Interface	TFT Module
(MDT0144ASS-MULTI)		Specification		
Version: 1 Date: 08/07/2021				
		Revision		
1	14/10/2020	First issue		
2	06/07/2021	Updated Brightness		

Display	Display Features						
Display Size	1.44"						
Resolution	128 x 128						
Orientation	Square						
Appearance	RGB						
Logic Voltage	3.3V						
Interface	Parallel/ SPI						
Brightness	200 cd/m ²	Roh	ant				
Touchscreen		Compi	anı				
Module Size	32.36 x 38.00 x 2.60mm						
Operating Temperature	-20°C ~ +70°C	,					
Pinout	30 way FFC	Box Quantity Weight /	Display				
Pitch		ure subnly-	-				
ure orgi							

* - For full design functionality, please use this specification in conjunction with the ST7735S specification.(Provided Separately)

Display Accessories					
Part Number	Description				

Optional Variants						
Appearances	Voltage					

General Description

* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorp hous silicon TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 1.44'TFT-LCD contains 128x128pixels, and c an display up to 65K colors.

* Features

-Low Input Voltage: 3.3V (TYP) -Display Colors of TFT LCD: 65K colors

-RGB Interface: - 8/16-BIT 8080 MCU interface

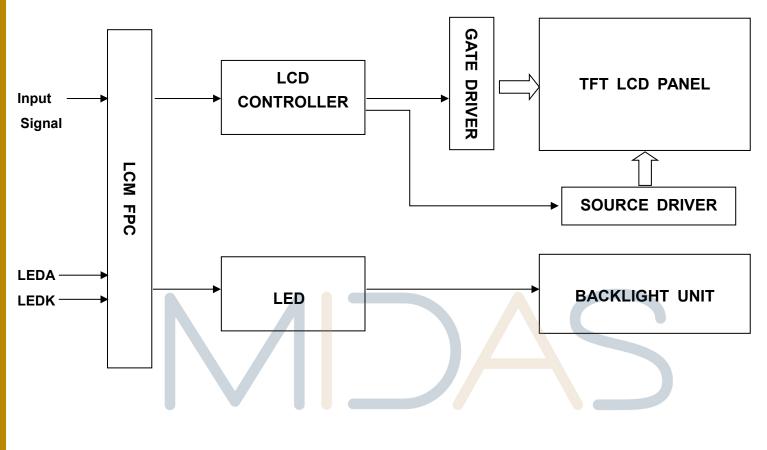
- 3/4-line SPI

General Information	Specification	Unit	Note	
ltems	Main Panel			
Display area(AA)	25 <mark>.5</mark> 0(H)*26.50(V) (1.44inch)	mm	-	
Driver element	TFT active matrix	-	-	
Display colors	65K	colors	-	
Number of pixels	128(RGB)*128	dots	-	
Pixel arrangement	RGB vertical stripe	-	-	
Pixel pitch	0.1992(H)*0.207(V)	mm	-	
Viewing angle		o'clock	ly <u>-</u>	
TFT Driver IC	ST7735S	-	-	
Display mode	TN/ Normally white	-	-	
Operating temperature	-20~+70	°C	-	
Storage temperature	-30~+80	°C	-	

* Mechanical Information

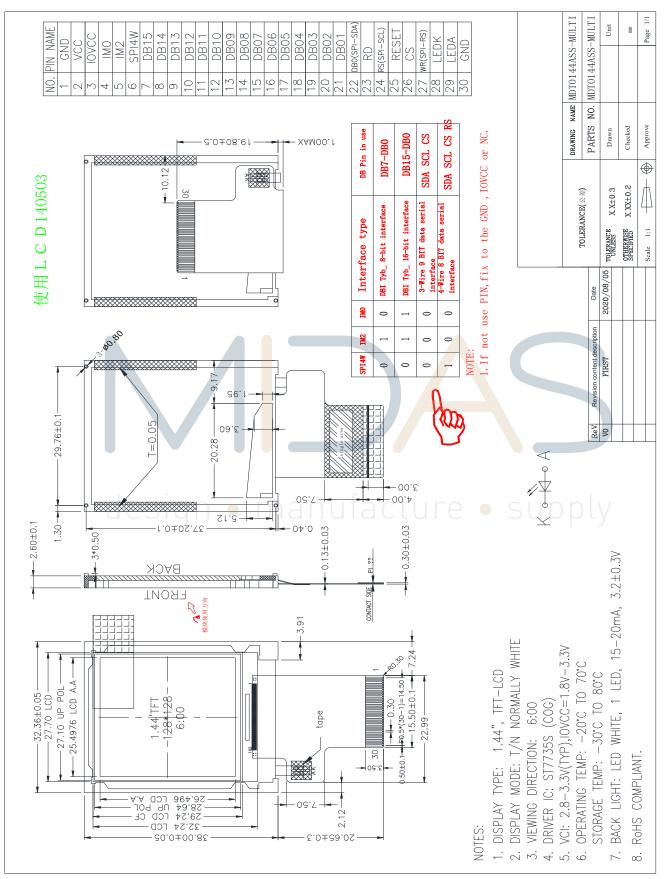
Item		Min.	Тур.	Max.	Unit	Note
Modulo	Horizontal(H)		32.36		mm	-
Module size	Vertical(V)		38.00		mm	-
3120	Depth(D)		2.60		mm	-
	Weight		TBD		g	-

1. Block Diagram



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Outline dimension



Input terminal Pin Assignment

		-	
NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	Р
2	VCC	Supply voltage (3.3V).	Р
3	IOVCC	Supply voltage for I/O.(1.8V-3V)	Р
4	IMO	IM0='1', MCU 8-bit parallel. IM0='0', MCU 16-bit parallel.	
5	IM2	MCU parallel interface and serial interface select. IM2='1', Parallel Interface. IM2='0', Serial Interface.	I
6	SPI4W	 SPI4W='0', 3-line SPI Enable. SPI4W='1', 4-line SPI Enable. If not used, Fix this pin to DGND. 	I
7	DB15		I/O
8	DB14		I/O
9	DB13		I/O
10	DB12		1/0
11	DB11		I/O
12	DB10 CE	sign • manufacture • s	upplyo
13	DB09	 DB[15:0] are used as MCU parallel interface data bus 	I/O
14	DB08	- DB0 is the serial input/output signal in serial	I/O
15	DB07	interface mode.	I/O
16	DB06	 In serial interface, DB[15:1] are not used and should be fixed at GND. 	I/O
17	DB05		I/O
18	DB04		I/O
19	DB03		I/O
20	DB02		I/O
21	DB01		I/O
22	DB0(SPI-SDA)		I/O
23	RD	Read Enable in 8080 MCU Parallel Interface.	I

24	RS(SPI-SCL)	Ι	
25	RESET	This signal will reset the device and must be applied to properly initialize the chip.	Ι
26	CS	Chip Selection Pin -Low Enable.	I
27	WR(SPI-RS)	-Write enable in MCU parallel interface. -In 4-line SPI, this pin is used as RS (data/ command selection). -If not used, please fix this pin at IOVCC or GND.	I
28	LEDK	Cathode pin of backlight.	Р
29	LEDA	Anode pin of b <mark>a</mark> cklight.	Р
30	GND	Ground.	Р

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LCD Optical Characteristics

1. Optical specification

ltem		Symbol Condition		Min.	Тур.	Max.	Unit.	Note
	Transmittance (with Polarizer)				5			
Contrast R	atio	CR	Θ=0	500	700			
Response	Rising	T _R	Normal viewing		5	10		
time	Falling	T _F	angle		15	25	msec	
Color gan	nut	S(%)			40		%	
				0.263	0.303	0.343		
	White	W _Y		0.285	0.325	0.365		
	Rx		0.555	0.575	0.595			
Color Filter	Red	Ry		0.31	0.33	0.35		
Chromacicity		Gx		0.321	0.341	0.361		
	Green	Gy		0.578	0.598	0.618		
		Bx		0.132	0.152	0.172		
	Blue	B _Y		0.04	0.06	0.08		
	fdes	Θι	manu	ia <u>c</u> tt	60	<u>sup</u> p	oty	
	Hor.	Θr			60			
Viewing angle	Ver.	Θυ	CR>10		30			
		ΘD			60			
Option View D	irection			6 O'clock	<			

*The data comes from the LCD specification.

Measuring Condition

Measuring surrounding : dark room

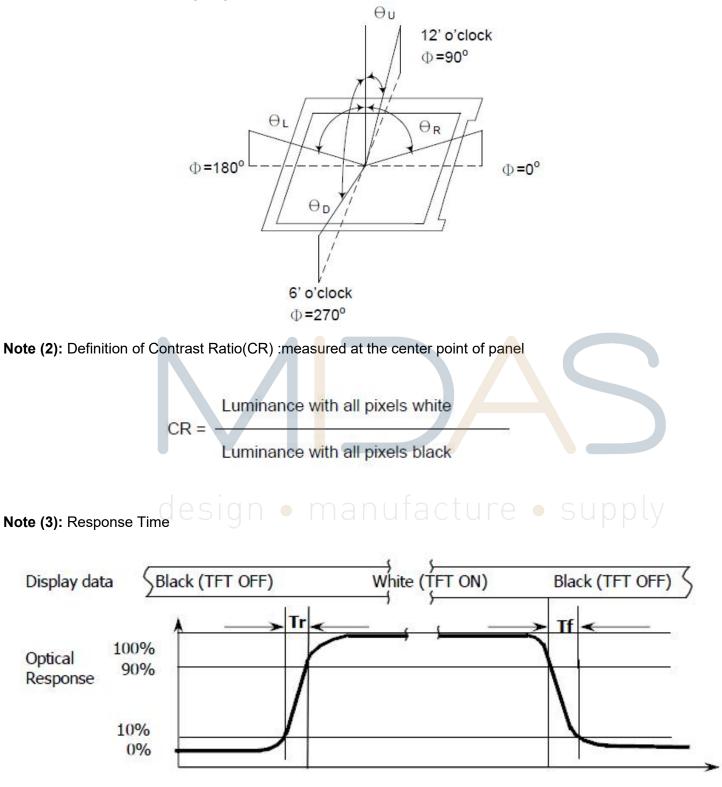
Ambient temperature : 25±2°C

15min. warm-up time.

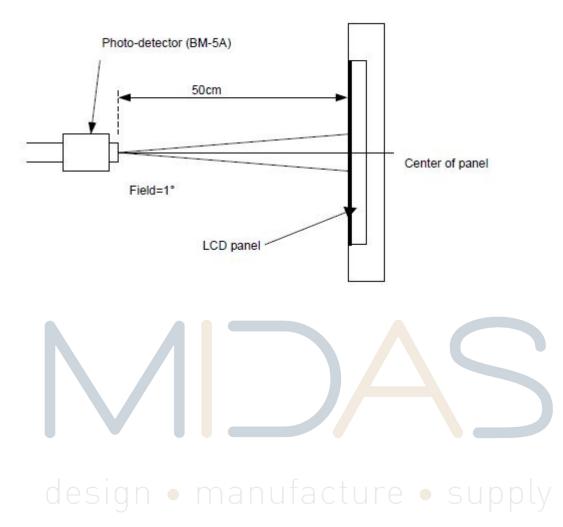
Measuring Equipment

FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

Note (1): Definition of Viewing Angle :



Note (4): Definition of optical measurement setup



Electrical Characteristics

1. Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VDD	-0.3	4.8	V
Digital interface supple Voltage	VDDIO	-0.3	4.6	V
Operating temperature	T _{OP}	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

2. DC Electrical Characteristics

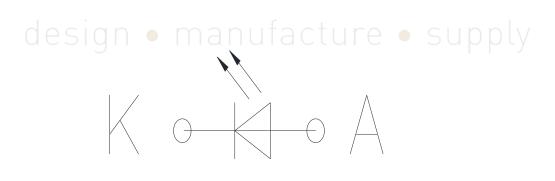
Electrical Characteristics	ΛΓ					
Characteristics	Sym <mark>b</mark> ol	Min.	Тур.	Max.	Unit	Note
Digital Supply Voltage	VDD	2.4	3.3	4.8	V	
Digital interface supple Voltage	VDDIO	1.65	3.3	4.8	V	
Normal mode Current	• ma IDD	inurad 	1.2	• sup 	mA	
	VIH	0.7Vddio		VDDIO	V	
Level input voltage	VIL	GND		0.3Vddio	V	
	V _{OH}	0.8VDDIO		VDDIO	V	
Level output voltage	V _{OL}	GND		0.2VDDIO	V	

3. LED Backlight Characteristics

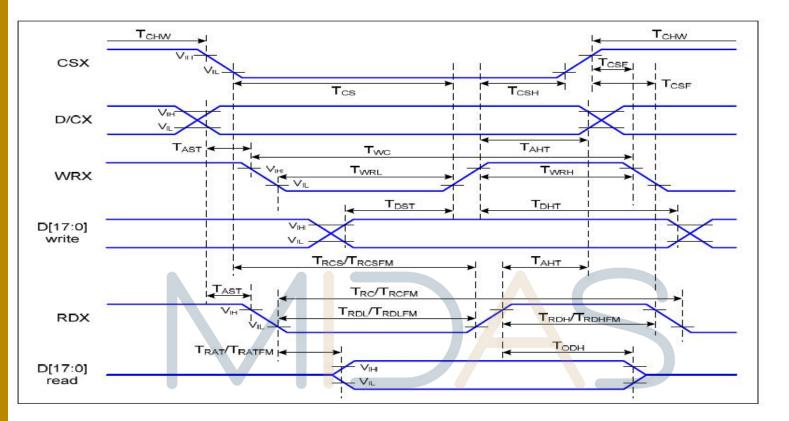
Item	Symbol	Min.	Тур.	Max.	Unit	Note
Forward Current	I _F	15	20		mA	
Forward Voltage	VF		3.2		V	
LCM Luminance	Lv	200			cd/m2	lf=20mA
LED life time	Hr	50000			Hour	Note1,2
Uniformity	AVg	80			%	

The back-light system is edge-lighting type with 1 chips White LED

Note (1) LED life time (Hr) can be defined as the time in which it continues to operate under the condition:
Ta=25±3 ℃, typical IL value indicated in the above table until the brightness becomes less than 50%.
Note (2) The "LED life time" is defined as the module brightness decrease to 50% original brightness at Ta=25℃ and IL=20mA. The LED lifetime could be decreased if operating IL is larger than 20mA. The constant current driving method is suggested.



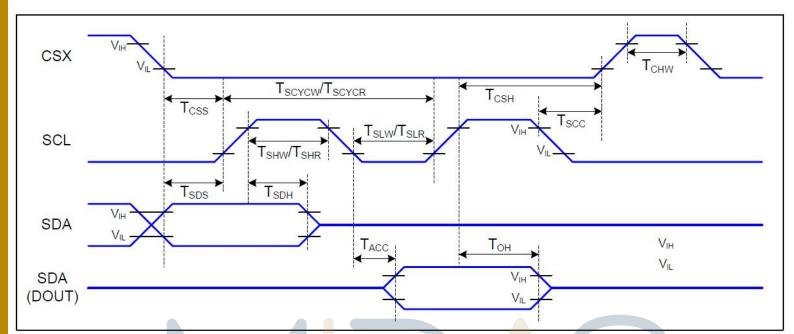
AC Characteristic



1. 8080 Series MCU Parallel Interface Timing Characteristics: 16/8-bit Bus

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Ta=25 °C, VDDI=1.65~3.7V, VDD=2.5~4.8V
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Signal	Symbol	Parameter	Min	Мах	Unit	Description
D/CX	TAST	Address Setup Ttime	0		ns	
DICX	TAHT	Address Hold Time (Write/Read)	10		ns	1-
	TCHW	Chip Select "H" Pulse Width	0		ns	
	TCS	Chip Select Setup Time (Write)	15		ns]
csx	TRCS	Chip Select Setup Time (Read ID)	45		ns	
037	TRCSFM	Chip Select Setup time (Read FM)	355		ns] -
	TCSF	Chip Select Wait Time (Write/Read)	10		ns	
2	TCSH	Chip Select Hold Time	10		ns	
	TWC	Write Cycle	66		ns	
WRX	TWRH	Control Pulse "H" Duration	15		ns]
	TWRL	Control Pulse "L" Duration	15		ns	
	TRC	Read Cycle (ID)	160		ns	
RDX (ID)	TRDH	Control Pulse "H" Duration (ID)	90		ns	When Read ID Data
	TRDL Control Pulse "L" Duration (ID)		45		ns]

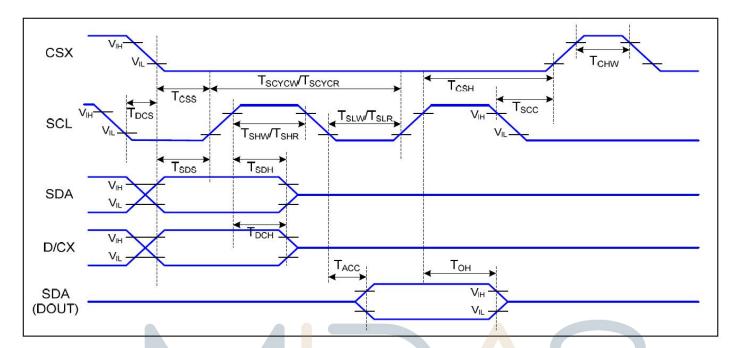


2. Serial Interface Characteristics (3-line Serial)

Ta=25 °C, VDDI=1.65~3.7V, VDD=2.5~4.8V

Signal	Symbol	Symbol Parameter Min		Max	Unit	Description
	TCSS	Chip Select Setup T <mark>im</mark> e (Write)	15		ns	
	TCSH	Chip Select Hold Time (Write)	15		ns	
CSX	TCSS	Chip Select Setup Time (Read)	60		ns	
	TSCC	Chip Select Hold Time (Read)	65	ure	ns	uppty
	TCHW	Chip Select "H" pulse width	40	2	ns	
	TSCYCW	Serial Clock Cycle (Write)	66		ns	
	TSHW	SCL "H" Pulse Width (Write)	15		ns	
SCL	TSLW	SCL "L" Pulse Width (Write)	15		ns	
SUL	TSCYCR	Serial Clock Cycle (Read)	150		ns	
	TSHR	SCL "H" Pulse Width (Read)	60		ns	
	TSLR	SCL "L" Pulse Width (Read)	60		ns	
0.5.4	TSDS	Data Setup Time	10		ns	
SDA	TSDH	Data Hold Time	10		ns	For Maximum CL=30pF
(DIN) (DOUT)	TACC	Access Time	10	50	ns	For Minimum CL=8pF
	тон	Output Disable Time	15	50	ns	

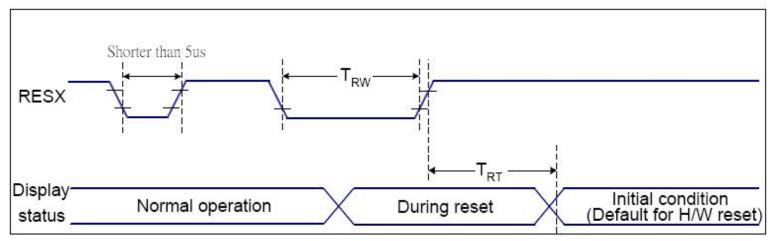
3. Serial Interface Characteristics (4-line Serial)



Ta=25 °C, VDDI=1.65~3.7V, VDD=2.5~4.8V

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
	TCSS	Chip Select Setup Time (Write)	45		ns	
	TCSH	Chip Select Hold Time (Write)	45		ns	
CSX	TCSS	Chip Select Setup Time (Read)	60		ns	
	TSCC	Chip Select Hold Time (Read)	65	ire	ns	sunnly
	TCHW	Chip Select "H" Pulse Width	40		ns	pappty
	TSCYCW	Serial Clock Cycle (Write)	66		ns	-Write Command &
	TSHW	SCL "H" Pulse Width (Write)	15		ns	Data Ram
SCL	TSLW	SCL "L" Pulse Width (Write)	15		ns	
SUL	TSCYCR	Serial Clock Cycle (Read)	150		ns	-Read Command &
	TSHR	SCL "H" Pulse Width (Read)	60		ns	-Read Command & Data Ram
	TSLR	SCL "L" Pulse Width (Read)	60		ns	Data Nam
D/CX	TDCS	D/CX Setup Time	10		ns	
DICA	TDCH	D/CX Hold Time	10		ns	
004	TSDS	Data Setup Time	10		ns	
SDA	TSDH	Data Hold Time	10		ns	For Maximum CL=30pF
(DIN) (DOUT)	TACC	Access Time	10	50	ns	For Minimum CL=8pF
	тон	Output Disable Time	15	50	ns	

4. Reset Timing Characteristics



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70 ℃

Related Pins	Symbol	Parameter	MIN	MAX	Unit
	TRW	Reset pulse duration	10	-	US
RESX	TRT Reset cancel			5 (Note 1, 5)	ms
	I.K.	Reset cancer		120 (Note 1, 6, 7)	ms

Notes:

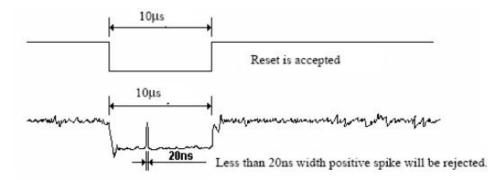
1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



5. When Reset applied during Sleep In Mode.

6. When Reset applied during Sleep Out Mode.

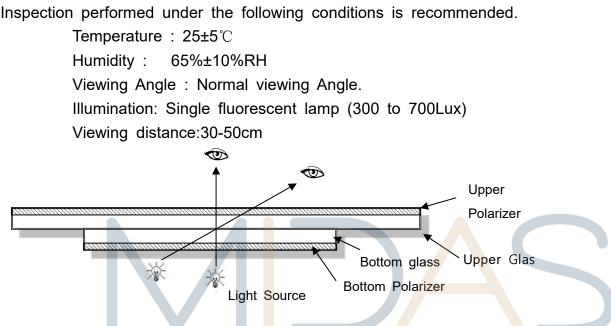
7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.



LCD Module Out-Going Quality Level

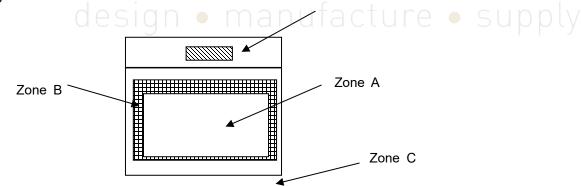
1. VISUAL & FUNCTION INSPECTION STANDARD

1.1 Inspection conditions



1.2 Definition

Zone D



Zone A: Effective Viewing Area (Character or Digit can be seen)

Zone B: Viewing Area except Zone A

Zone C: Outside (Zone A+Zone B) which can not be seen after assembly by customer.)

Zone D: IC Bonding Area

Note:

As a general rule, visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer

1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class $\rm II$ AQL:

Major defect	Minor defect
0.65	1.5

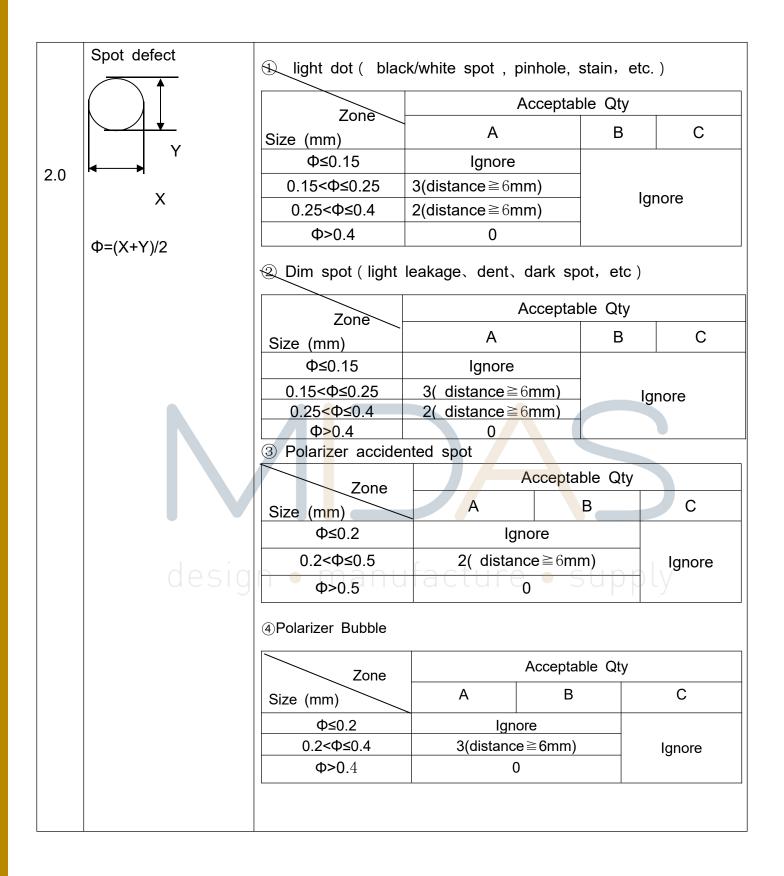
LCD: Liquid Crystal Display, TP: Touch Panel, LCM: Liquid Crystal Module

No	Items to be insp	Criteria	Classification of de
	ected		fects
		1) No display, Open or miss line	
1	Functional defects	2) Display abnormally, Short	
	Functional delects	3) Backlight no lighting, abnormal lighting.	
			Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawi	
5		ng is not allowed	
4	Color tone	Color unevenness, refer to limited sample	
5	Soldering appeara	Good sold <mark>er</mark> ing, Peeling off is not allowed.	Minor
5	nce		
6	LCD/Polarizer	Black/White spot/line, scratch, crack, etc.	

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1.4 Criteria (Visual)

Number	Items		Criteria(mm)		
1.0 LCDCrack/BrokenNOTE:X: LengthY: WidthZ: Height	(1) The edge of LCD broken				
L: Length of IT		Х	Y	Z	
O, T: Height of LCD		≤3.0mm	<inner border="" line="" of="" t<br="">he seal</inner>	≤T	
	(2)LCD corner broken	$\begin{array}{c c} \hline \\ \hline $			
C	esign ● ma (3) LCD crack	inutact		oly	
			Crack Not allowed		



3.0	LCD Pixel defect	Pixel bad po	ints	
		Item	Zone A	Acceptable Qt
			Random	N≤2
		Bright dot	2 dots adjacent	N≤0
			3 dots adjacent	N≤0
			Random	N≤2
		Dark dot	2 dots adjacent	N≤0
			3 dots adjacent	N≤0
		Distance	 Minimum Distance Between Bright dots. Minimum Distance Between dark dots Minimum Distance Between dark and bright dot. 	5mm
	desig	Total bright	and dark dot	N≤4
		LCD pane B) Dark dot:	: Dots appear bright and unchanged el is displaying under black pattern. Dots appear dark and unchanged in el is displaying under pure red, green	size in which
		C) 2 dot adj Picture:	acent = 1 pair = 2 dots	
		2 dot adj	acent 2 dot adjacer	nt
		2 dot adjace	ent (vertical) 2 dot adjacen	nt (slant)

	Line defect (LCD /Polarizer backlight bla		Length(m	Acce	eptable C)tv
	ck/white line, scratch,	Width(mm)	m)	A	B	C
	stain)	Ф≤0.03	Ignore	Ignore	;	
4.0	₩ W	0.03 <w≤0.04< td=""><td>L≤3.0</td><td>N≤2</td><td></td><td>Ignore</td></w≤0.04<>	L≤3.0	N≤2		Ignore
	W: width, L : length	0.04 <w≤0.05< td=""><td>L≤2.0</td><td>N≤1</td><td></td><td></td></w≤0.05<>	L≤2.0	N≤1		
	N : Count	W>0.05 Define as spot defect				
5.0	Electronic Componen ts SMT.	Not allow missing parts, solderless connection, cold solder joint, m smatch, The positive and negative polarity opposite				
6.0	Display color& Brigh tness.	 Color: Measuring the color coordinates, The measurement standard according to the datasheet or samples. Brightness: Measuring the brightness of White screen, The measurement standard according to the datasheet or Samples. 				
7.0	LCD Mura/Waving/ Hot spot	e if necessary.				by limit samı

Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed

Reliability Test Result

Item	Condition	Inspection after test
High Temperature Operating	70℃,96H	
Low Temperature Operating	-20°C, 96HR	
High Temperature Storage	80°C, 96HR	
Low Temperature Storage	-30°C, 96HR	Inspection after 2~4hours storage at room temperature, the
High Temperature & High Humidity Operating	+60℃, 90% RH ,96 hours.	sample shall be free from defects:
Thermal Shock (Non- operation)	-10°C,30 min ↔ +60°C,30 min,	1.Air bubble in the LCD; 2.Non-display;
ESD test	C=150pF, R=330,5points/panel Air:±8KV, 5times; Contact:±6KV, 5 times;	3.Missing segments/line; 4.Glass crack; 5.Current IDD is twice higher
Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition).	than initial value.
Box Drop Test	1 Corner 3 Edges 6 faces,80cm(MEDIUM BOX)	

Remark:

1. The test samples should be applied to only one test item.

2.Sample size for each test item is 5~10pcs.

3.For Damp Proof Test, Pure water(Resistance > $10M\Omega$) should be used.

4. In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.

5.Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

6. The color fading mura of polarizing filter should not care.

Cautions and Handling Precautions

1. Handling and Operating the Module

(1) When the module is assembled, it should be attached to the system firmly.

Do not warp or twist the module during assembly work.

(2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.

(3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.

(4) Do not allow drops of water or chemicals to remain on the display surface.

If you have the droplets for a long time, staining and discoloration may occur.

(5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.

(6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.

Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.

(7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.

(8) Protect the module from static; it may cause damage to the CMOS ICs.

(9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.

(10) Do not disassemble the module.

(11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.

(12) Pins of I/F connector shall not be touched directly with bare hands.

(13) Do not connect, disconnect the module in the "Power ON" condition.

(14) Power supply should always be turned on/off by the item 6.1 Power On Sequence &6.2 Power Off Sequence

2. Storage and Transportation.

(1) Do not leave the panel in high temperature, and high humidity for a long time.

It is highly recommended to store the module with temperature from 0 to 35 $^{\circ}$ C and relative humidity of less than 70% (2) Do not store the TFT-LCD module in direct sunlight.

(3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.

(4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.

In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.

(5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.

